

03-07-2005



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To the Director of the U.S. Patent and Trademark Office: Please record the attached documents or the new address(es) below.

02/22/05

1. Name of conveying party(ies)/Execution Date(s):

Robert Wayne Donis

Execution Date(s) 18 FEB 2005

Additional name(s) of conveying party(ies) attached?  Yes  No

2. Name and address of receiving party(ies)

Name: LSI Logic Corporation

Internal Address: \_\_\_\_\_

Street Address: 1621 Barber Lane

City: Milpitas

State: California

Country: USA Zip: 95035

Additional name(s) & address(es) attached?  Yes  No

3. Nature of conveyance:

- Assignment  Merger
- Security Agreement  Change of Name
- Government Interest Assignment
- Executive Order 9424, Confirmatory License
- Other \_\_\_\_\_

4. Application or patent number(s):

This document is being filed together with a new application.

A. Patent Application No.(s)

B. Patent No.(s)

Additional numbers attached?  Yes  No

5. Name and address to whom correspondence concerning document should be mailed:

Name: LSI Logic Corporation

Internal Address: MS: D-106 LEGAL

Street Address: 1621 Barber Lane

City: Milpitas

State: California Zip: 95035

Phone Number: 408-433-8000

Fax Number: 408-433-7460

Email Address: \_\_\_\_\_

6. Total number of applications and patents involved:

1

7. Total fee (37 CFR 1.21(h) & 3.41) \$ 40

- Authorized to be charged by credit card
- Authorized to be charged to deposit account
- Enclosed
- None required (government interest not affecting title)

8. Payment Information

a. Credit Card Last 4 Numbers \_\_\_\_\_  
Expiration Date \_\_\_\_\_

b. Deposit Account Number 12-2252

Authorized User Name Bradley D. Baugh

9. Signature:

Bradley D. Baugh  
Signature

22 FEB 2005

Date

Bradley D. Baugh

Name of Person Signing

Total number of pages including cover sheet, attachments, and documents:

4

Documents to be recorded (including cover sheet) should be faxed to (703) 306-5995, or mailed to:  
Mail Stop Assignment Recordation Services, Director of the USPTO, P.O.Box 1450, Alexandria, V.A. 22313-1450

03/04/2005 REGISTRY 0000007 122252 11063384

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PATENT  
REEL: 016338 FRAME: 0150

113211 U.S. PTO  
11/063384



022205

**Title:** Systems And Methods For Wafer Polishing  
**Inventors:** Robert Wayne Donis  
**Filed:** To Be Filed  
**Serial Number:** Unassigned  
**Client Docket No.:** 04-2163  
**Attorney Docket No.:** 20020-1043

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## ASSIGNMENT

For good and valuable consideration, the receipt of which is hereby acknowledged, the individual(s) named below (hereinafter "INVENTOR" whether singular or plural) has sold, assigned, transferred, and set over, and hereby sells, assigns, transfers and sets over, to LSI Logic Corporation, a corporation of the State of Delaware, having a place of business at 1621 Barber Lane, Milpitas, CA 95035 ("ASSIGNEE"), for itself and its successors, transferees, and assignees, the following:

1. The full and exclusive worldwide right, title, and interest in and to all inventions and improvements ("SUBJECT MATTER") that are disclosed in the U.S. patent application, entitled "SYSTEMS AND METHODS FOR WAFER POLISHING" ("APPLICATION"),

which is a provisional application

bearing Application No. \_\_\_\_\_, and filed on \_\_\_\_\_;

to be filed herewith; or

which is a non-provisional application

bearing Application No. \_\_\_\_\_, and filed on \_\_\_\_\_;

to be filed herewith;

having an oath or declaration executed on the same date as this Assignment;

having an oath or declaration executed on a different date than this Assignment.

2. The entire worldwide right, title, and interest in and to the APPLICATION and all applications claiming priority to the APPLICATION or having related SUBJECT MATTER to the APPLICATION, including all such utility, divisional, continuation, substitute, renewal, reissue or other related application and all rights of priority in the APPLICATION, together with all rights to recover damages for infringement of provisional rights.

INVENTOR hereby authorizes and requests the Director of the U.S. Patent and Trademark Office, and Patent Office Officials in all foreign countries, to issue to the ASSIGNEE any and all patents which may be granted from the APPLICATION.

INVENTOR will, without further consideration, communicate to the ASSIGNEE any facts known to the INVENTOR regarding the SUBJECT MATTER, testify in any legal proceeding, sign all lawful papers, execute all oaths, assignments, powers of attorney, applications and any other paper desired by ASSIGNEE to obtain, perfect, or secure to ASSIGNEE any and all of the rights, titles and interests herein conveyed, and to maintain, enforce, and defend these rights, titles and

**Title:** Systems And Methods For Wafer Polishing  
**Inventors:** Robert Wayne Donis  
**Filed:** To Be Filed  
**Serial Number:** Unassigned  
**Client Docket No.:** 04-2163  
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interests in the United States and all foreign countries. INVENTOR further agrees to provide any successor, assign, or legal representative of ASSIGNEE with the benefits and assistance provided to ASSIGNEE herein.

INVENTOR represents that the INVENTOR, at the time of the execution of this Assignment, is the sole and lawful owner of the entire rights, titles and interests in and to the SUBJECT MATTER as set forth in the APPLICATION, and that the SUBJECT MATTER is unencumbered, and that the INVENTOR has good and full right and lawful authority to sell and convey the SUBJECT MATTER in the manner herein set forth.

INVENTOR covenants with ASSIGNEE that the INVENTOR has not made and will not hereafter make any assignment, grant, mortgage, license or other agreement affecting the rights, titles, and interests herein conveyed.

INVENTOR agrees to, and hereby acknowledges, that the ASSIGNEE may apply for and receive patents related to the APPLICATION or SUBJECT MATTER.

INVENTOR grants the attorney of record for the APPLICATION the power to insert on this Assignment any further identification, including the application number and filing date, which may be necessary or desirable to comply with the rules of the United States Patent and Trademark Office for recordation of this document.

This Assignment may be executed in one or more counterparts, each of which shall be deemed an original and all of which may be taken together as one and the same Assignment. One inventor/assignor signature block is located on the following page.

**Title:** Systems And Methods For Wafer Polishing  
**Inventors:** Robert Wayne Donis  
**Filed:** To Be Filed  
**Serial Number:** Unassigned  
**Client Docket No.:** 04-2163  
**Attorney Docket No.:** 20020-1043

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**INVENTOR Name:** Robert Wayne Donis  
**INVENTOR Address:** 5590 I Street  
Washougal, WA 98671  
**Date of Signature:** 2/18/05

  
 \_\_\_\_\_  
 [INVENTOR Signature]

On \_\_\_\_\_, before me \_\_\_\_\_ personally appeared  
 [Date] [Notary Public]

\_\_\_\_\_ personally known to me or proved to me on the basis of  
 [INVENTOR]  
 satisfactory evidence to be the person whose name is subscribed to the within instrument and  
 acknowledging to me that [he/she] executed the same in [his/her] authorized capacity, and that  
 by [his/her] signature on the instrument the person, or the entity upon behalf of which the person  
 acted, executed the instrument

\_\_\_\_\_  
 Notary

Notary Seal